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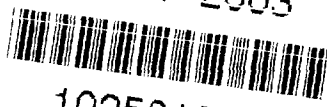
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Form PTO-1595

(Rev. 03/01)

OMB No. 0651-0027 (exp. 5/31/2002)

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U.S. DEPARTMENT OF COMMERCE
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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Miyazaki Mitsuhiro

8.15.03

2. Name and address of receiving party(ies)

Name: Hakko Corporation

Internal Address: _____

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:



Assignment



Merger



Security Agreement



Change of Name



Other

Street Address: _____

4-5, Shiokusa, 2-chome,
Naniwa-ku, Osaka 556-0024 JAPAN

City: _____ State: _____ Zip: _____

Execution Date: August 7, 2003

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)

29/178,911

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☐ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Sung I. Oh, Esq.

Squire, Sanders & Dempsey L.L.P.
801 South Figueroa Street
14th Floor
Los Angeles, California 90017-5554

6. Total number of applications and patents involved:

7. Total fee (37 CFR 3.41).....\$ 40.00



Enclosed



Authorized to be charged to deposit account

8. Deposit account number:

07-1853

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Sung I. Oh Reg. No. 45,583

Name of Person Signing

Signature

August __, 2003

Date

Total number of pages including cover sheet, attachments, and documents:

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Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

Doc. ID Los Angeles 49044.1

PATENT
REEL: 014397 FRAME: 0134

ASSIGNMENT

WHEREAS, I, Miyazaki Mituhiko, residing at 6-25-503 Higashi-yama-cho, Higashi-osaka-city, Osaka, Japan, the undersigned inventor and the ASSIGNOR herein, have invented **FLANGE FOR A SOLDERING CARTRIDGE**, for which an application for a U.S. Design Patent was filed on April 1, 2003 and assigned Serial Number 29/178,911, and of which inventions and improvements I am the sole owner; and

WHEREAS, Hakko Corporation, is a corporation organized and existing under the laws of Japan, having a place of business at 4-5, Shiokusa, 2-chome, Naniwa-ku, Osaka 556-0024, Japan, the ASSIGNEE herein, desires to acquire the entire right, title and interest in and to said inventions, applications and Letters Patent to be granted and issued thereon;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) by the ASSIGNEE to me paid, and other valuable consideration, the receipt and legal sufficiency of all of which is hereby acknowledged, I, the said ASSIGNOR, have sold and do hereby sell, assign, transfer and set over unto said ASSIGNEE, its successors and assigns, the entire right, title and interest in and to said inventions and all improvements thereon, in and to said application for Letters Patent thereon, in and to applications pertaining to or based upon said inventions and applications, including divisional and continuing applications and continuations-in-part, and in and to any and all Letters Patent which may be granted and issued on said inventions and applications, or any of them, not only for, to and in the United States of America, its territories and possessions, but for, to and in all countries foreign thereto, together with and including all priority rights based upon any and all applications in the United States of America covered by this Assignment.

And for the above-named considerations, I do hereby agree that I will, at the request of said ASSIGNEE, execute any and all applications for Letters Patent for said inventions and any and all other papers and documents and do all other and further lawful acts that said ASSIGNEE may deem necessary or desirable to obtain Letters Patent on said inventions, to secure the grant of such Letters Patent and to perfect and vest in the ASSIGNEE the entire right, title and interest in the inventions, applications and Letters Patent.

And for the above-named considerations, I do hereby authorize and empower the ASSIGNEE, its successors and assigns, to apply for and obtain, in its or their own names, Letters Patent for the said inventions before competent International Authorities and in any and all countries foreign to the United States in which applications for Letters Patent can be so made or Letters Patent so obtained.

Dated: August, 7, 2003

By Mituhiko Miyazaki
Miyazaki Mituhiko